

MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

LCD MODULE SPECIFICATION

Model: MI240160E-G-1

This module uses ROHS material

For Customer's Acceptance:

Customer	
Approved	
Comment	

This specification may change without prior notice in
order to improve performance or quality. Please contact
Multi-Inno for updated specification and product status
before design for this product or release of this order.

Revision	1.1
Engineering	
Date	2013-10-09
Our Reference	



RECORDS OF REVISION

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
04/08/2010	01		New Drawing		
05/02/2010	1.0		New Sample SPEC		
10/09/2013	1.1		Correct IO description		



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1. SPECIFICATIONS

1.1 Features

Item	Standard Value			
Display Type	240*160 Dots			
LCD Type	FSTN, Transflective, Positive, Extended Temp.			
Driver Condition	LCD Module: 1/160 Duty, 1/14Bias			
Viewing Direction	6 O'clock			
Backlight	White			
Weight	30.5g			
Interface	Support 8 Bit Parallel interface with 8080 / 6800 MPU			
Other(controller / driver IC)	SITRONIX – ST7586S			
ROHS				

1.2 Mechanical Specifications

Item	Standard Value	
Outline Dimension	83.8 (L) * 60.0(w) * 6.7(H)	mm
Viewing Area	69.6 (L) * 47.6 (w)	mm
Active Area	65.985 (L) * 43.985 (w)	
Dot Size	0.26 (L) * 0.26 (w)	mm
Dot Pitch	0.275 (L) * 0.275 (w)	mm

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	VDD	_	-0.3	3.6	V
LCD Driver Supply Voltage	V0-XV0	_	-0.3	19	V
Input Voltage	V _{IN}	_	-0.3	VDD+0.3	V
Operating Temperature	T_{OP}	_	-10	60	°C
Storage Temperature	T_{ST}	_	-20	70	$^{\circ}\!\mathbb{C}$
Storage Humidity	H_D	Ta < 60 °C	-	90	%RH



1.4 DC Electrical Characteristics

VSS= 0V, $Ta = 25^{\circ}C$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	VDD	-	2.7	3	3.3	V
"H" Input Voltage	V _{IH}	-	0.7VDD	-	VDD	V
"L" Input Voltage	V_{IL}	-	VSS	-	0.3VDD	V
Supply Current	I_{DD}	VDD=3V;VOP=17.5V; Pattern= Full display	-	1.6	-	mA
		VDD=3V;VOP=17.5V; Pattern= Horizontal line*1	-	2.8	5.0	1117 \$
		-10°C	17.9	18.1	18.3	
LCM Driver Voltage	VOP*2	25℃	17.3	17.5	17.7	V
		60℃	15.7	15.9	16.1	

NOTE: *1 The Maximum current display

^{*2} The VOP test point is V0- XV0



1.5 Optical Characteristics

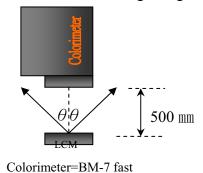
LCD Panel: 1/160Duty, 1/14Bias, VLCD=17.5V, Ta =25°C

Item		Symbol	Conditions	Min.	Тур.	Max.	Unit	Reference
Response Time	Rise	tr		-	150	225	ma	Note2
Response Time	Fall	tf		-	370	555	ms	Note2
	Тор	ΘY+	C≥2.0,	-	40	_		
Viewing angle	Bottom	ΘΥ-	Ø =270°	-	40	-	Dag	Notes 1
range	Left	ΘX-		-	40	-	Deg.	Notes 1
	Right	ΘХ+		-	40	-		
Contrast Rat	io	С	$\theta = 0^{\circ},$ $\varnothing = 270^{\circ}$	-	6.9	-	-	Note 3
Average Bright (with LCD)		IV	VF=3.2V	30	45	-	cd/m ²	Note 4
Uniformity *1		△B		70	-	-	%	

Note 4:

- 1 : △B=B(min) / B(max) * 100%
- 2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25° C $\pm 5^{\circ}$ C / $60\pm 20^{\circ}$ R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b: Measurement Distance: $500 \pm 50 \text{ mm}$, $(\theta = 0^{\circ})$
 - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
 - d : The uncertainty of the C.I.E coordinate measurement ± 0.01 , Average Brightness $\pm\,4\%$





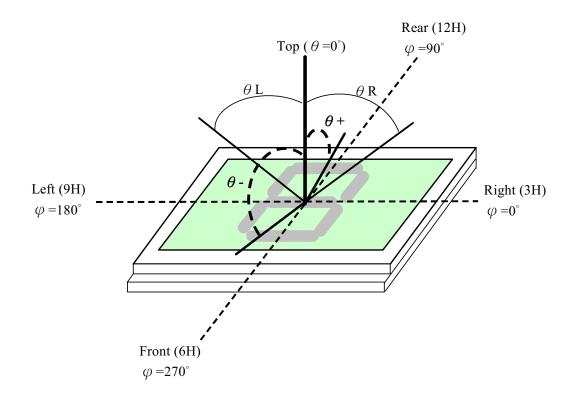
P.6



Note 1.

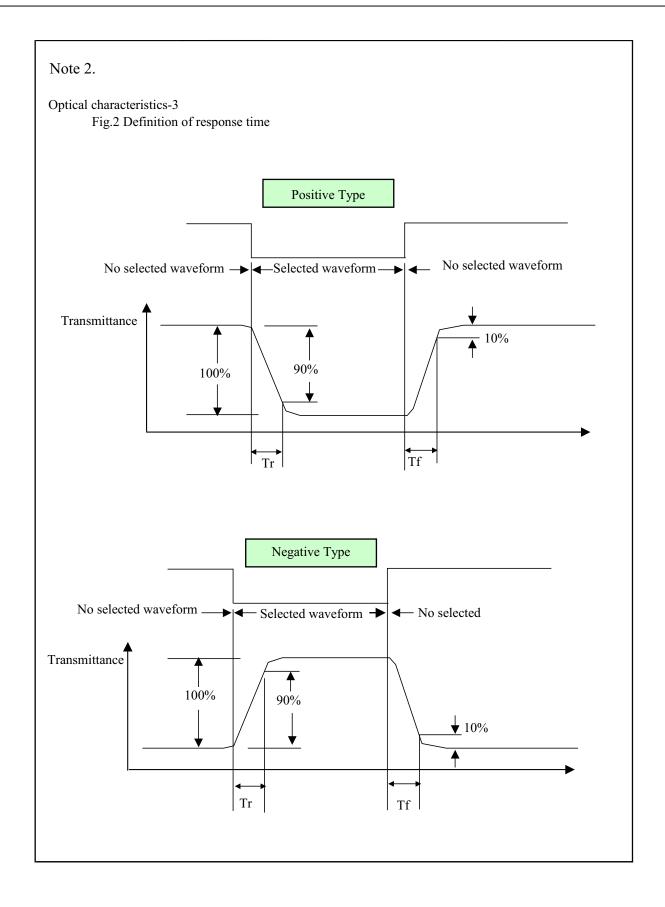
Optical characteristics-2

Viewing angle



Viewing angle







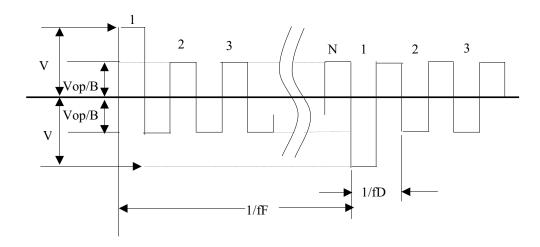
Electrical characteristics-2

※2 Drive waveform

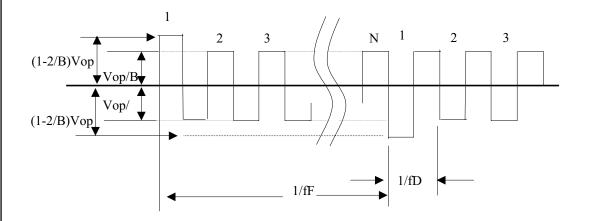
Vop: Drive voltage fF: Frame frequency 1/B: Bias fD: Drive frequency

N: Duty

(1) Selected waveform



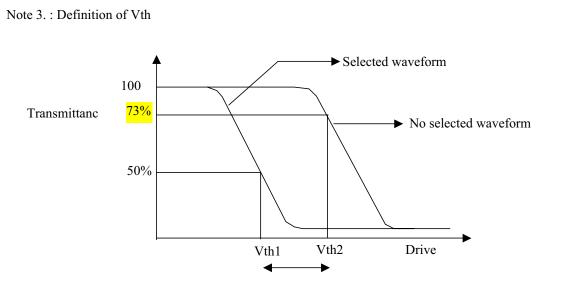
(2) Non- Selected wave form



Note:

Frame frequency is defined as follows: Common side supply voltage peak - to - peak /2 = 1 period





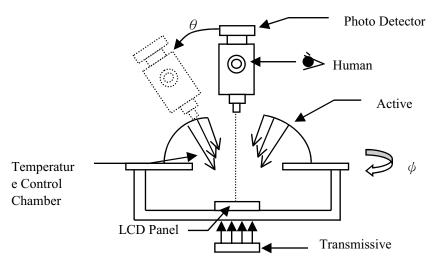
Active voltage range

	Vth1	Vth2
View direction	10 °	40 °
Drive waveform	(Selected waveform)	(No selected waveform)
Transmittance	50%	73%

※1 Contrast ratio

= (Brightness in OFF state) / (Brightness in ON state)

Outline of Electro-Optical Characteristics Measuring System



Measuring System: Autronic DMS-803



1.6 Backlight Characteristics

LCD Module with LED Backlight

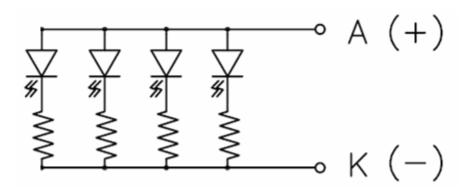
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°C	-	100	mA
Reverse Current	IF	Vr=4V	-	200	uA
Power Dissipation	PD	Ta =25°C	-	240	mW

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Current	VF		-	80	100	mA
Average Brightness (without LCD)	IV	VF=3.2V	200	500	-	cd/m ²
CIE Color Coordinate	X		0.27	-	0.30	-
(Without LCD)*	Y		0.275	-	0.305	
Color			White			

Internal Circuit Diagram:



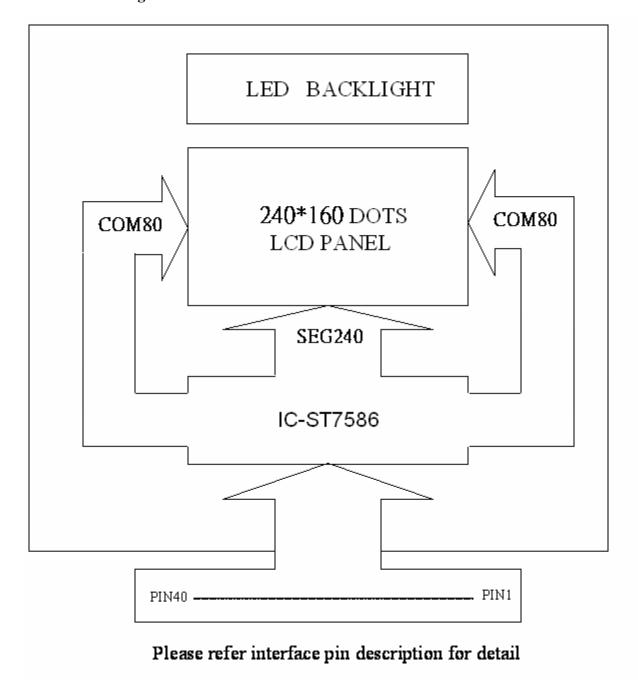
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





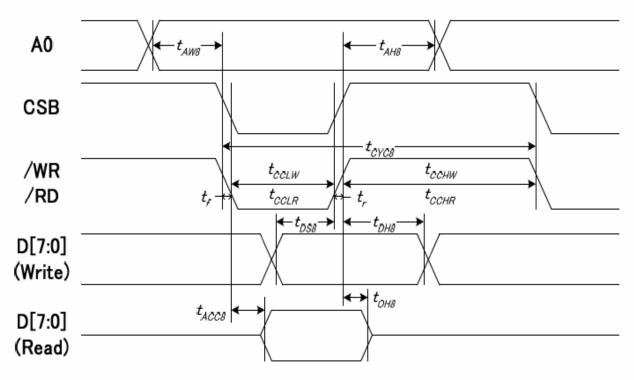


2.2 Interface Pin Description

2.2 Interface Pin Description							
Pin No.	Symbol	Function					
1	Α	ower supply for Backlight (anode)					
2	K	Power supply for Backlight (cathode)					
		Register select input pin					
3	A0	− A0 = "H": DB0 to DB7 are display data					
		- A0 = "L": DB0 to DB7 are control data					
4	WR	Write signal. Low active					
5	DB0						
6	DB1						
7	DB2						
8	DB3	The 8 bit bi-directional bus					
9	DB4	The oblibilational bus					
10	DB5						
11	DB6						
12	DB7						
13	RD	Read signal, low active					
14	RES	Reset input pin. When RST is "L", initialization is executed.					
15	IF2	These pins select interface operation mode.					
	IF1	IF2 IF1 MPU interface type					
16		H L 80 series 8-bit parallel					
		L L 68 series 8-bit parallel					
		Chip select input pin					
17	XCS	Data/instruction I/O is enabled only when XCS is "L". When chip select is					
		non-active, DB0 to DB7 may be high impedance.					
18	VDD	Power supply for LCD model (VDD=3.0 V)					
19	VSS	Power ground					
20	VDD	Power supply for LCD mode (VDD=3.0 V)					
21-33	NC	Not used					
34	VM	LCD bias supply voltage					
35	V0	Positive LCD driver supply voltages					
36	XV0	Negative LCD driver supply voltages					
37	VG	Bias LCD driver supply voltages					
38	VD1	Connect a capacitor between VD1 and VSS					
39-40	NC	Not used					

2.3 Timing Characteristics

System Bus Timing for 8080 MCU Interface



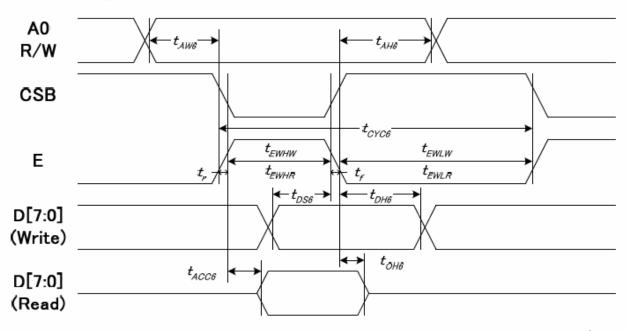
ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	A0	tAW8		0	_	
Address hold time	Au	tAH8		0	1	
System cycle time (WRITE)		tCYC8		240	_	
WR L pulse width (WRITE)	WR	tCCLW		100		
WR H pulse width (WRITE)		tCCHW		100	_	
System cycle time (READ)		tCYC8		500	_	ns
/RD L pulse width (READ)	RD	tCCLR		220		115
/RD H pulse width (READ)		tCCHR		220		
WRITE Data setup time		tDS8		20	_	
WRITE Data hold time	D[7:0]	tDH8		20	_	
READ access time	D[1.0]	tACC8	CL = 30 pF	_	100	
READ Output disable time		tOH8	CL = 30 pF	10	110	

Note:

- The input signal rise time and fall time (tr, tf) is specified at 15 ns or less. When the system cycle time is extremely fast, (tr + tf) ≤ (tCYC8 – tCCLW – tCCHW) for (tr + tf) ≤ (tCYC8 – tCCLR – tCCHR) are specified.
- 2. All timing is specified using 20% and 80% of VDD1 as the reference.
- 3. tCCLW and tCCLR are specified as the overlap between CSB being "L" and WR and RD being at the "L" level.



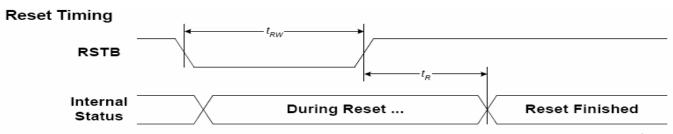
System Bus Timing for 6800 MCU Interface



ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	A0	tAW6		0	_	
Address hold time	AU	tAH6		0	_	
System cycle time (WRITE)		tCYC6		240	_	
Enable L pulse width (WRITE)		tEWLW		100	_	
Enable H pulse width (WRITE)	E	tEWHW		100	_	
System cycle time (READ)	_	tCYC6		500		ns
Enable L pulse width (READ)		tEWLR		220	_	115
Enable H pulse width (READ)		tEWHR		220		
Write data setup time		tDS6		20	_	
Write data hold time	D(7:01	tDH6		20	_	
Read data access time	D[7:0]	tACC6	CL = 16 pF	_	100	
Read data output disable time		tOH6	CL = 16 pF	10	110	

Note:

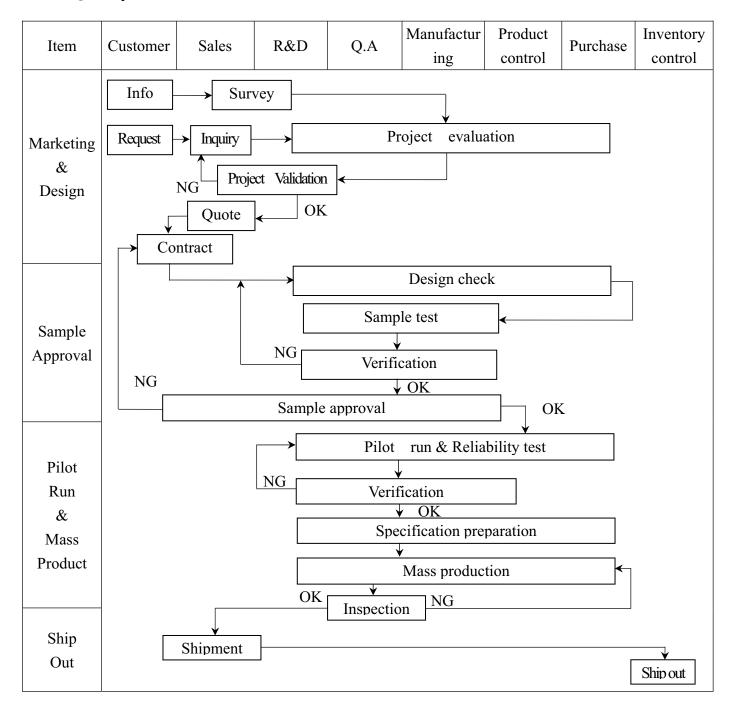
- 1. The input signal rise time and fall time (tr, tf) is specified at 15 ns or less. When the system cycle time is extremely fast, $(tr + tf) \le (tCYC6 tEWLW tEWHW)$ for $(tr + tf) \le (tCYC6 tEWLR tEWHR)$ are specified.
- 2. All timing is specified using 20% and 80% of VDD1 as the reference.
- 3. tEWLW and tEWLR are specified as the overlap between CSB being "L" and E.



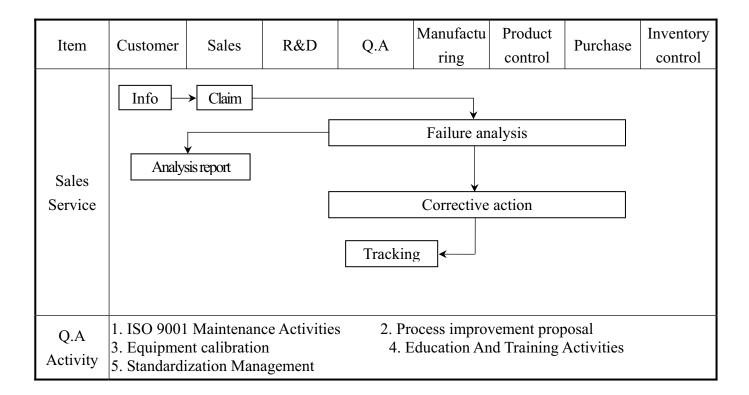
ltem	Symbol	Condition	Min.	Max.	Unit
Reset time	tR		120	_	ms
Reset "L" pulse width	tRW		10	_	us

3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2. Inspection Specification

- ◆Scope: The document shall be applied to LCD Module for Monotype and Color STN(Ver. B01).
- ◆Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment : Gauge · MIL-STD · Powertip Tester · Sample
- ◆Defect Level: Major Defect AQL: 0.4 ; Minor Defect: AQL: 1.5.
- OUT Going Defect Level : Sampling .
- **◆**Manner of appearance test :
 - (1). The test be under 20W×2 fluorescent light 'and distance of view must be at 30 cm.
 - (2). Standard of inspection: (Unit: mm)
 - (3). The test direction is base on about around 45° of vertical line. (Fig. 1)
 - (4). Definition of area . (Fig. 2)

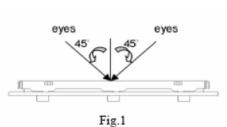


Fig. 2 A area : viewing area

B area : Outside of viewing area

♦ Specification:

NO	Item	Criterion	Level
		1. 1 The part number is inconsistent with work order of Production.	Major
01	Product condition	1. 2 Mixed production types.	Major
		1. 3 Assembled in inverse direction.	Major
02	Quantity	2. 1 The quantity is inconsistent with work order of production.	Major
03	Outline dimension	3. 1 Product dimension and structure must conform to Structure diagram.	Major
		4. 1 Missing line character and icon.	Major
		4, 2 No function or no display.	Major
04	Electrical Testing	4. 3 Output data is error.	Major
		4, 4 LCD viewing angle defect.	Major
		4. 5 Current consumption exceeds product specifications.	Major



◆Specification For Monotype and Color STN:

⊷ R∩1`	(W
r bui	L Vet
1.001	vei.

NO	Item		Criterion						
	Black or white dot \ scratch \ contamination	 5. 1 Round type: 5. 1. 1 display only: • White and black spots on display ≤ 0, 30 mm, no more than 4 white or black spots present. • Densely spaced: NO more than two spots or lines within 3 mm. 							
	Round type	I	display : mension meter : Φ)		Acceptance A area	(Q't			
	-al. lat.		$\Phi \leq 0.10$		ept no dense	ъ	area		
05	1 x Y Y	0.10 <	< Φ ≤ 0.20		3			3.5.	
05	<u> </u>	$0.20 < \Phi \leq 0.30$			2		gnore	Minor	
	$\Phi = (x+y)/2$	Total quantity			4				
		5, 1, 3 Line type:							
	Line type	Dimension Length (L) Width (W)		Acceptance (Q'ty) A area B area					
	$\longrightarrow_{L} \stackrel{\stackrel{\blacklozenge}{\downarrow}}{\longleftarrow} W$	+		$W \leq 0.03$		Accept no de			
		$L \le 3.0$ $0.03 < W \le 0$). 05			Ignore		
		L ≤ 2.5	$0.05 < W \le 0.$	075					
			$\mathbf{W} > 0$. 075	As	roun	d type		
		Dim	nension		Acceptan	co (O	P(tv)		
			eter : Φ)		A area	B area			
			$\Phi \leq 0.20$	Ac	cept no dense				
06	Polarizer	0.20 <	$\Phi \leq 0.50$	3				Minor	
	Bubble	0.50 <	$\Phi \leq 1.00$	2		Ignore		MIHOL	
			$\Phi > 1.00$	0					
		Total	quantity		4				
				•		·			





♦Specification For Monotype and Color STN:

NO	Item		Criterion		Level	
	Item The crack of glass	Symbols: X: The length Z: The thicks t: The thicks	Criterion of crack Y: ness of crack W: ness of glass a: glass chip:	erack Y: The width of crack. of crack W: terminal length of glass a: LCD side length s chip: nel surface and crack between panels: Z Z X Y [NG]		
		X	Seal width Z	Y		
			Crack can't enter			
		≤ a	viewing area	≦1/2 t		
		≦ a	Crack can't exceed the half of SP width.	$1/2 t < Z \leq 2 t$		



MODULE NO.: MI240160E-G-1 Ver 1.1

♦Specification For Monotype and Color STN:

NO	Item		Criterion		Level	
		Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 7. 1. 2 Corner crack:				
ı		X	Y	z		
		≤1/5 a	Crack can't enter viewing area	Z ≤ 1/2 t		
	The crack of	≤1/5 a	Crack can't exceed the half of SP width.	$1/2 t < Z \leq 2 t$		
07	The crack of glass	7. 2 Protrusion of 7. 2. 1 Chip on 6		X Y Z w z ≤ t	Minor	



 \spadesuit Specification For Monotype and Color STN :

NO	Item	Criterion	Level			
	Item	Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 7. 2. 2 Non-conductive portion:				
07	The crack of glass	X Y Z ≤1/3 a ≤W ≤t O If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode	Minor			
		terminal specifications. 7. 2. 3 Glass remain:				
		$\begin{array}{c cccc} X & Y & Z \\ & \leq a & \leq 1/3 \text{ W} & \leq t \end{array}$				



♦Specification For Monotype and Color STN:

NO	Item	notype and Color STN: Criterion	(Ver. B01) Level
		8. 1 Backlight can't work normally.	Major
08	Backlight elements	8. 2 Backlight doesn't light or color is wrong.	Major
	8. 3 Illur	8. 3 Illumination source flickers when lit.	Major
		9. 1 Pin type must match type in specification sheet.	Major
		9. 2 No short circuits in components on PCB or FPC.	Major
09	General appearance	9. 3 Product packaging must the same as specified on packaging specification sheet.	Minor
		9. 4 The folding and peeled off in polarizer are not acceptable.	Minor
		9. 5 The PCB or FPC between B/L assembled distance (PCB or FPC) is ≤1. 5 mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO.	TEST ITEM	Т	TEST CO	NDITION		
1	High Temperature Storage Test	Keep in 70 ±2°C 96 hrs Surrounding temperature	Keep in 70 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.			
2	Low Temperature Storage Test	Keep in -20 ±2°C 96 hrs Surrounding temperature	, then sto	rage at norma	al conditio	n 4hrs.
3	High Temperature / High Humidity Storage Test	Keep in 60°C / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)				n 4hrs.
4	Temperature Cycling Storage Test	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$				
5	ESD Test	Surrounding temperature, then storage at normal condition 4hrs. Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/- 1. Temperature ambiance: 15°C ~35°C 2. Humidity relative: 30% ~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF±10% 4. Discharge Resistance(Rd): 330 Ω±10% 5. Discharge, mode of operation: Single Discharge (time between successive discharges at least 1 sec)				nes arity +/-
6	Vibration Test (Packaged)	 (Tolerance if the output voltage indication: ±5%) Sine wave 10~55 Hz frequency (1 min/sweep) The amplitude of vibration: 1.5 mm Each direction (X \ Y \ Z) duration for 2 Hrs 				
7	Drop Test (Packaged)	Packing Wei 0 ~ 45.4 ~ 90.8 ~ 0ver 4 Drop Direction: %1 corne	45. 4 90. 8 454 454	122 76 61 46	2	

5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



6.OUTLINE

